



Material Content Data Sheet



Sales Product Name	TLE7259-3LE			Issued	1. August 2018			
MA#	MA001102860							
Package	PG-TSON-8-1			Weight*	27.00 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.290	4.78	4.78	47774	47774
leadframe	inorganic material	phosphorus	7723-14-0	0.003	0.01		109	
	non noble metal	zinc	7440-66-6	0.012	0.04		437	
	non noble metal	iron	7439-89-6	0.236	0.87		8746	
wire	non noble metal	copper	7440-50-8	9.586	35.51	36.43	355106	364398
	non noble metal	copper	7440-50-8	0.043	0.16	0.16	1588	1588
	encapsulation	organic material	carbon black	1333-86-4	0.030	0.11		1099
plastics		epoxy resin	-	1.528	5.66		56596	
	inorganic material	silicondioxide	60676-86-0	13.275	49.19	54.96	491782	549477
leadfinish	non noble metal	tin	7440-31-5	0.382	1.42	1.42	14158	14158
plating	noble metal	silver	7440-22-4	0.043	0.16	0.16	1610	1610
glue	plastics	epoxy resin	-	0.142	0.52		5249	
	noble metal	silver	7440-22-4	0.425	1.57	2.09	15746	20995
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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